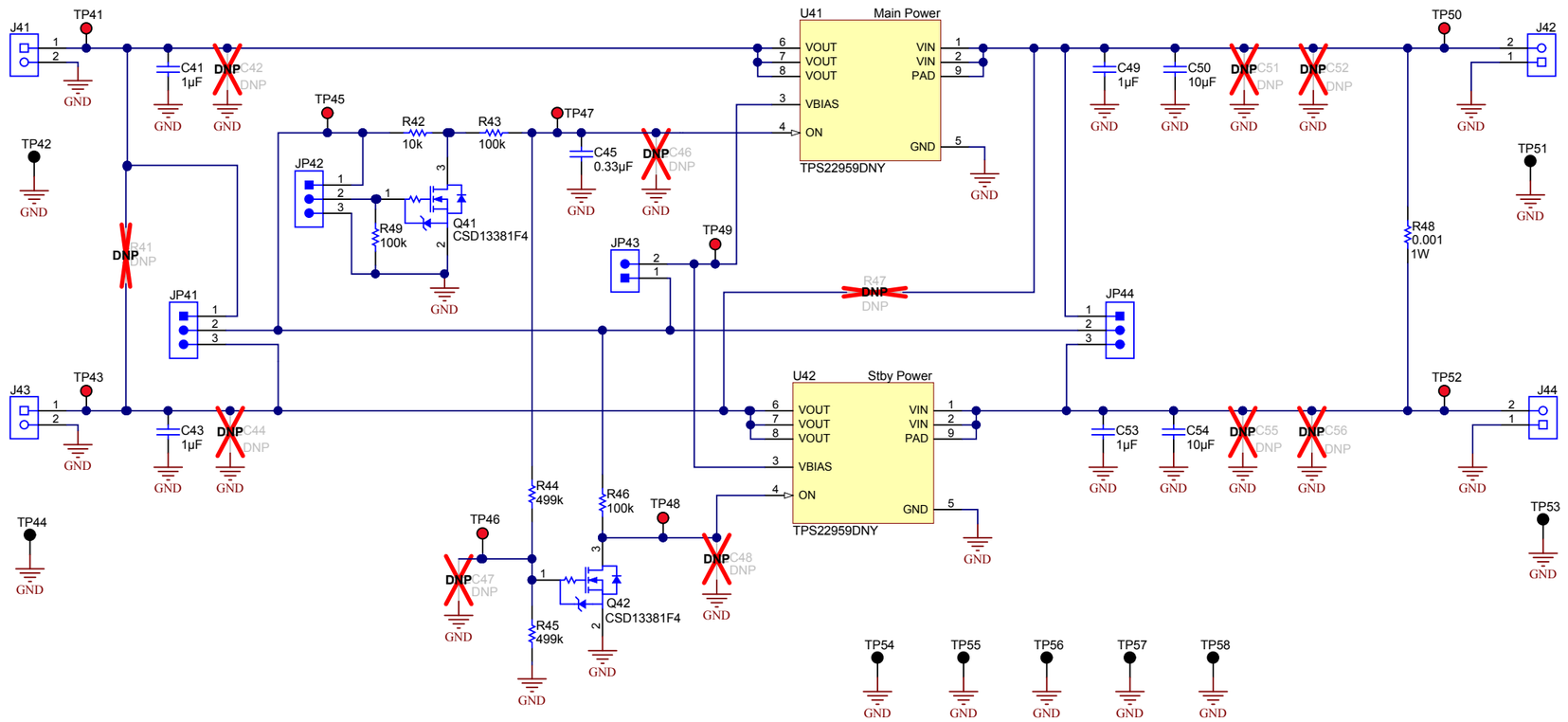
Power MUX



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 6/30/2015
TID #: 00514	Project Title: Load Switches for Power MUXing & Reverse Curren	
Number: TIDA-00514 Rev: A	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: TIDA-00514	Sheet: 2 of 3
Drawn By:	File: Power MUX (Reverse FET).SchDoc	Size: B
Engineer: Adam Hoover	Contact: http://www.ti.com/support	

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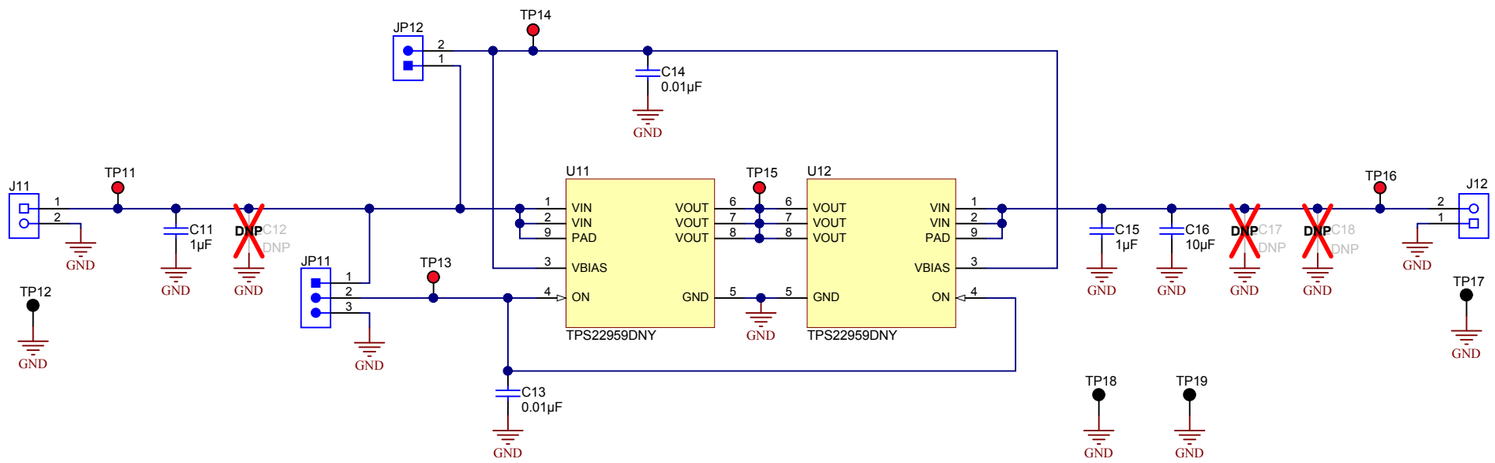
TPS22969/62/59 Reverse Current Protection (up to 15A)



Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 10/21/2014
TID #: 00514	Project Title: Load Switches for Power MUXing & Reverse Curren	
Number: TIDA-00514 Rev: A	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: TIDA-00514	Sheet: 2 of 3
Drawn By:	File: 15A RCP.SchDoc	Size: B
Engineer: Adam Hoover	Contact: http://www.ti.com/support	

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H9
SJ-5303 (CLEAR)

H10
SJ-5303 (CLEAR)

H11
SJ-5303 (CLEAR)

H12
SJ-5303 (CLEAR)

DNP
FID1

DNP
FID2

DNP
FID3

PCB Number: TIDA-00514
PCB Rev: A

PCB
LOGO
Texas Instruments

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

SH-JP11 SH-JP12 SH-JP21 SH-JP22 SH-JP31 SH-JP32 SH-JP41 SH-JP42 SH-JP43

Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 10/28/2014
TID #: 00514	Project Title: Load Switches for Power MUXing & Reverse Currer	
Number: TIDA-00514 Rev: A	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: TIDA-00514	Sheet: 3 of 3
Drawn By:	File: EVM_Hardware.SchDoc	Size: B
Engineer: Adam Hoover	Contact: http://www.ti.com/support	

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